

CLAIMS

- 5 1. Electroplatingplating solution for copper comprising $\text{CuSO}_4 \cdot 5\text{H}_2\text{O}$, H_2SO_4 , HCl , Polyethylenglycol (molecular weight >200), hydroxyl amine sulfate, hydroxyl amine chloride and if necessary further additives.
- 10 2. Solution according to claim 1 comprising Cl ions in a range of 50 – 150 ppm and hydroxyl amine sulfate in a range of 0,01 – 5 g/l.
- 15 3. Solution according to claim 1 comprising Cl ions in a range of 55 – 125 ppm.

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